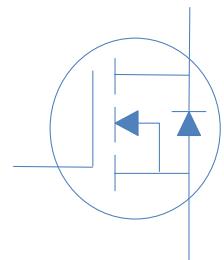
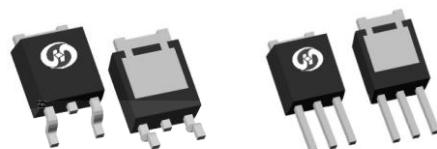


80V N-Ch Power MOSFET

V_{DS}	80	V
$R_{DS(on),typ}$	$V_{GS}=10V$	4.6 m
$R_{DS(on),typ}$	$V_{GS}=4.5V$	7.3 m
I_D (Silicon Limited)		88 A



Part Number	Package	Marking
HGD059N08AL	TO-252	GD059N08AL
HGI059N08AL	TO-251	GI059N08AL

Absolute Maximum Ratings at $T_J=25^\circ\text{C}$ (unless otherwise specified)

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	I_D	$T_C=25^\circ\text{C}$	88	A
		$T_C=100^\circ\text{C}$	62	
Drain to Source Voltage	V_{DS}	-	80	V
Gate to Source Voltage	V_{GS}	-	± 20	V
Pulsed Drain Current	I_{DM}	-	280	A
Avalanche Energy, Single Pulse	E_{AS}	$L=0.1\text{mH}, T_C=25^\circ\text{C}$	45	mJ
Power Dissipation	P_D	$T_C=25^\circ\text{C}$	94	W
Operating and Storage Temperature	T_J, T_{stg}	-	-55 to 175	$^\circ\text{C}$

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Ambient	R_{JA}	50	$^\circ\text{C/W}$
Thermal Resistance Junction-Case	R_{JC}	1.6	$^\circ\text{C/W}$

Electrical Characteristics at $T_J=25^\circ\text{C}$ (unless otherwise specified)
Static Characteristics

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\text{ A}$	80	-	-	V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=250\text{ A}$	1.4	1.9	2.4	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=80\text{V}, T_J=25^\circ\text{C}$	-	-	1	A
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=80\text{V}, T_J=100^\circ\text{C}$	-	-	100	
Gate to Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=20\text{A}$	-	4.6	5.9	m
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=4.5\text{V}, I_D=20\text{A}$	-	7.3	9.5	m
Transconductance	g_{fs}	$V_{\text{DS}}=5\text{V}, I_D=20\text{A}$	-	45	-	S
Gate Resistance	R_G	$V_{\text{GS}}=0\text{V}, V_{\text{DS}} \text{ Open}, f=1\text{MHz}$	-	1.1	-	

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=40\text{V}, f=1\text{MHz}$	-	2164	-	pF
Output Capacitance	C_{oss}		-	540	-	
Reverse Transfer Capacitance	C_{rss}		-	17	-	
Total Gate Charge	$Q_g(10\text{V})$	$V_{\text{DD}}=40\text{V}, I_D=20\text{A}, V_{\text{GS}}=10\text{V}$	-	43	-	nC
Total Gate Charge	$Q_g(4.5\text{V})$		-	22	-	
Gate to Source Charge	Q_{gs}		-	5	-	
Gate to Drain (Miller) Charge	Q_{gd}		-	14	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=40\text{V}, I_D=20\text{A}, V_{\text{GS}}=10\text{V}, R_G=10\text{ },$	-	10	-	ns
Rise time	t_r		-	8	-	
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	32	-	
Fall Time	t_f		-	10	-	

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_F=20\text{A}$	-	0.9	1.2	V
Reverse Recovery Time	t_{rr}	$V_R=40\text{V}, I_F=20\text{A}, dI_F/dt=400\text{A}/\text{s}$	-	33	-	ns
Reverse Recovery Charge	Q_{rr}		-	99	-	nC

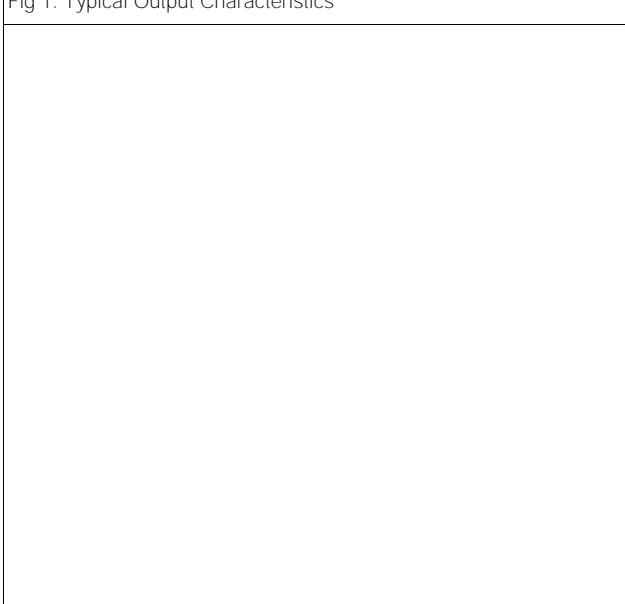
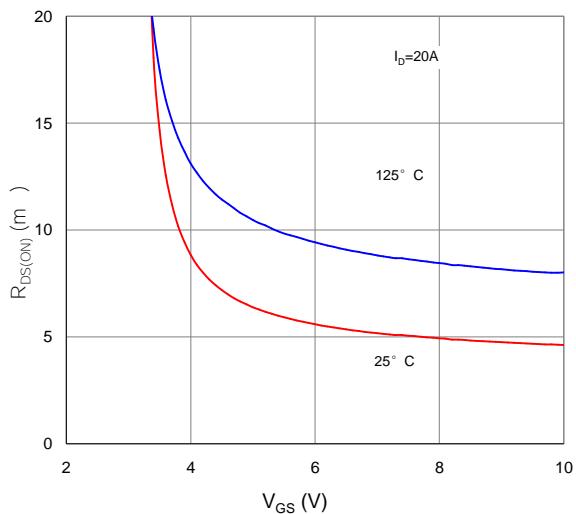
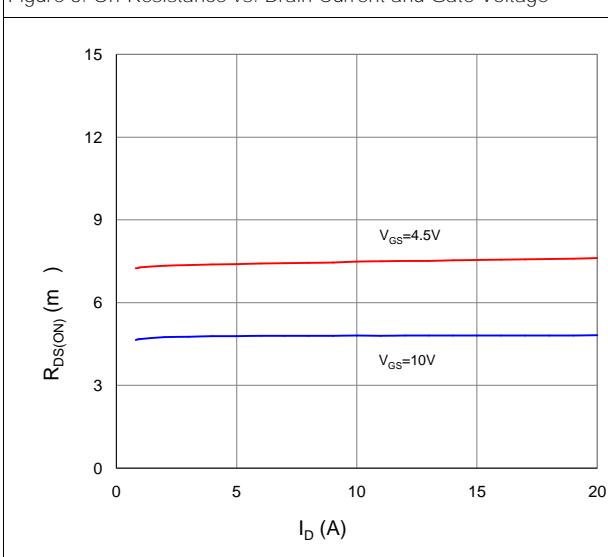
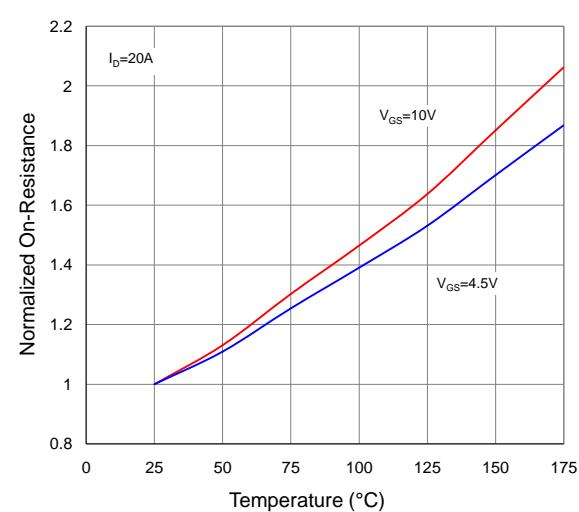
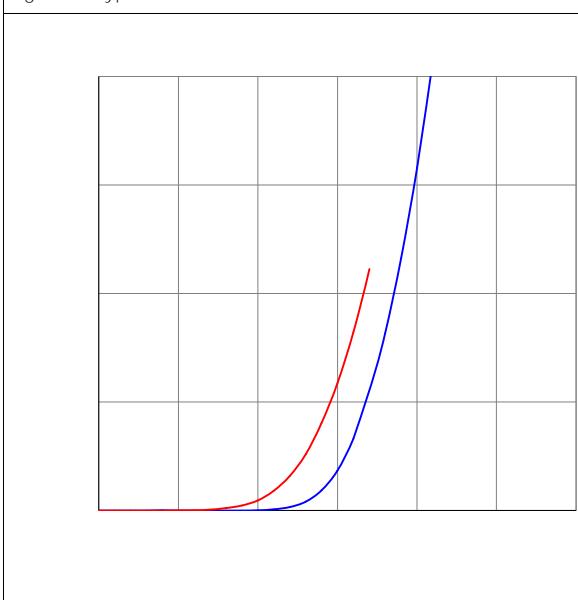
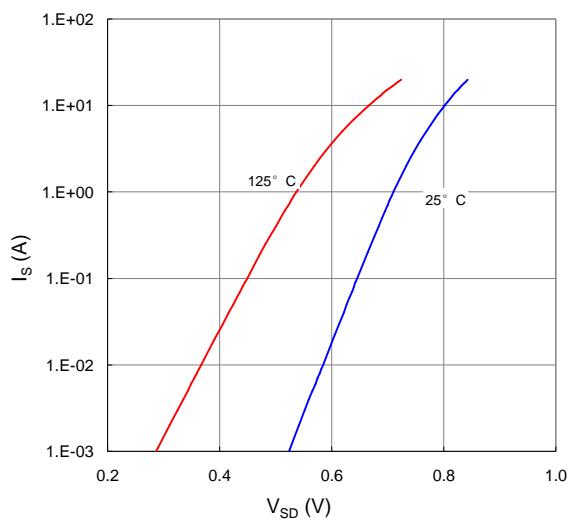
Fig 1. Typical Output Characteristics

Figure 2. On-Resistance vs. Gate-Source Voltage

Figure 3. On-Resistance vs. Drain Current and Gate Voltage

Figure 4. Normalized On-Resistance vs. Junction Temperature

Figure 5. Typical Transfer Characteristics

Figure 6. Typical Source-Drain Diode Forward Voltage


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

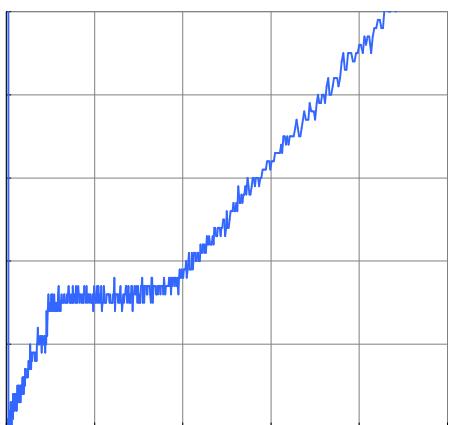
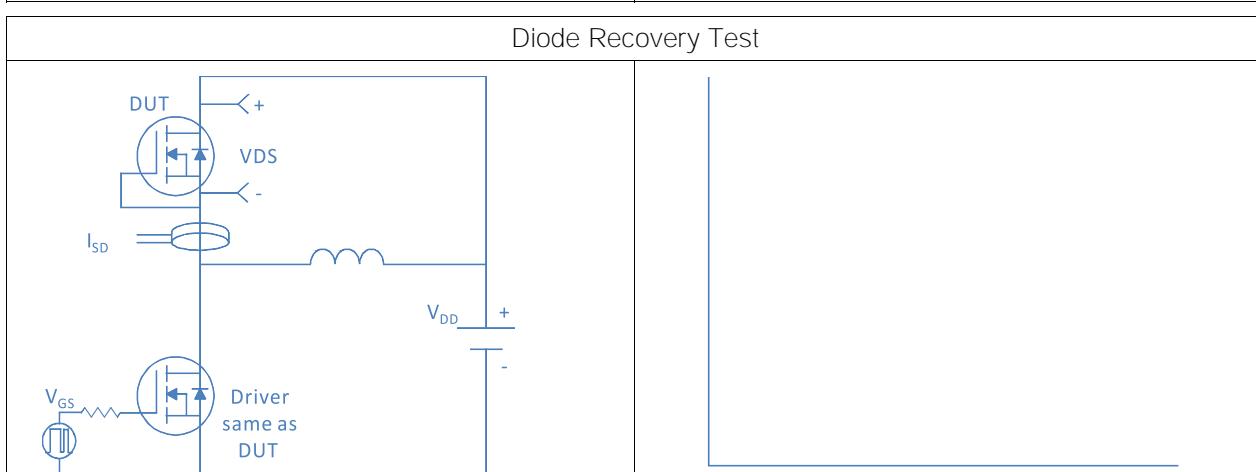
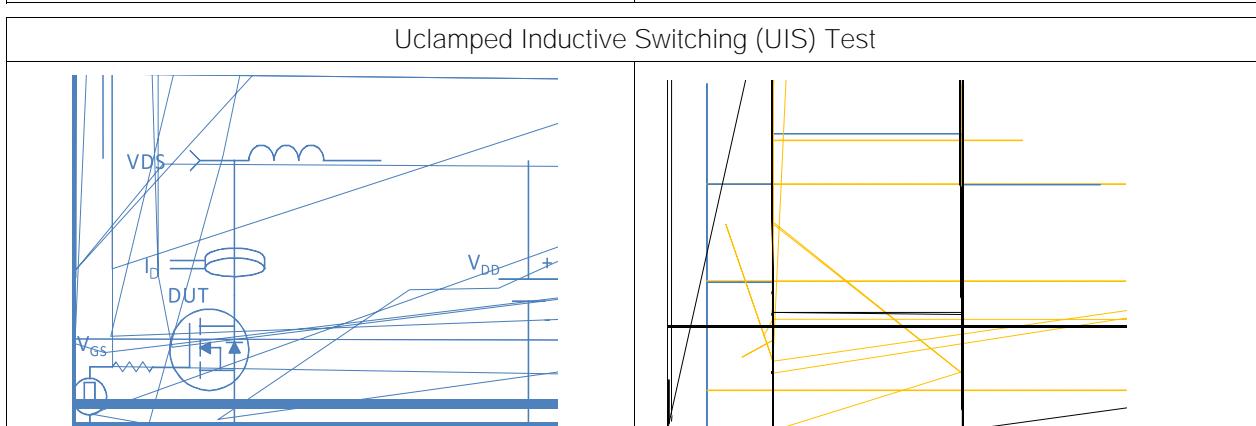
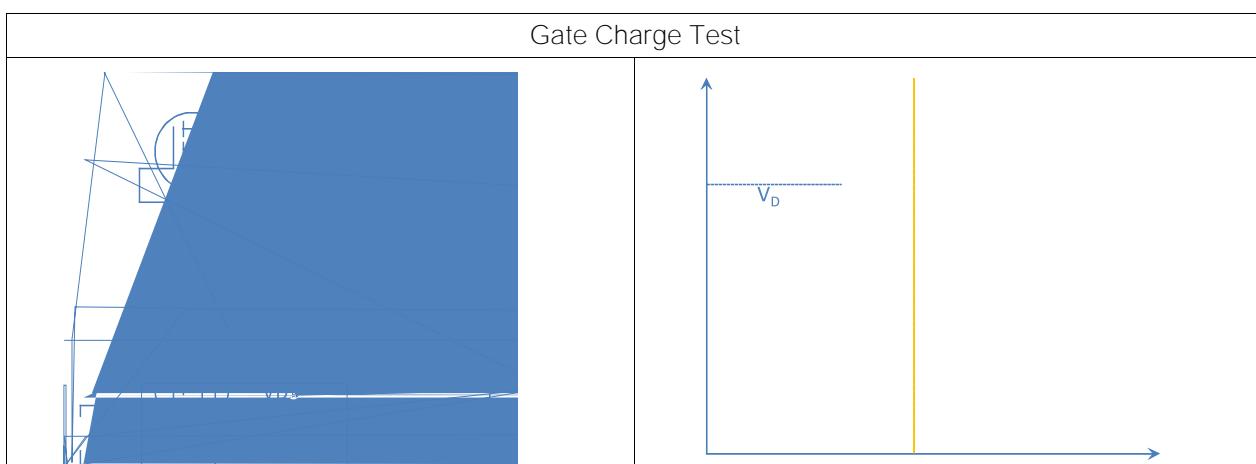
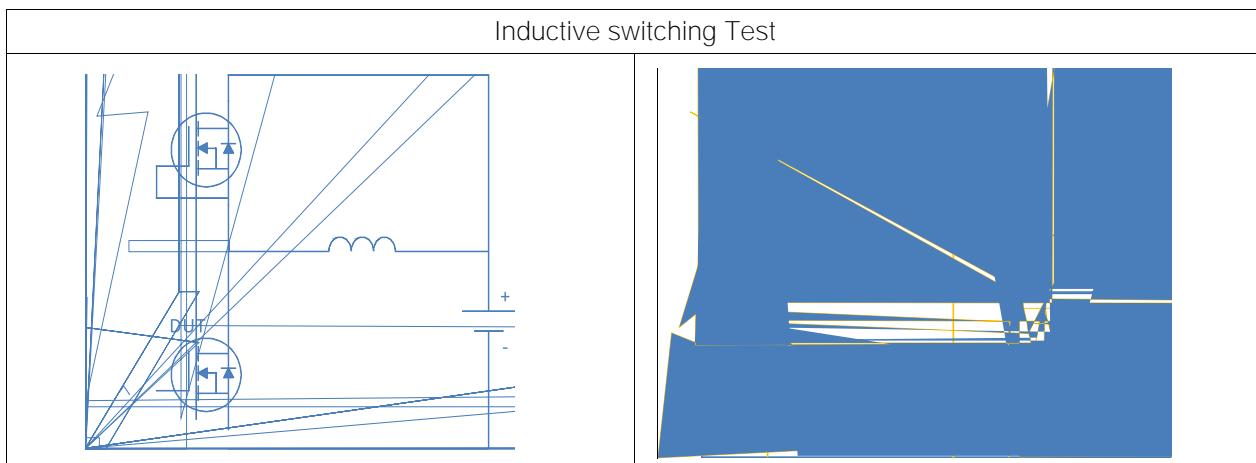


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

Figure 9. Maximum Safe Operating Area

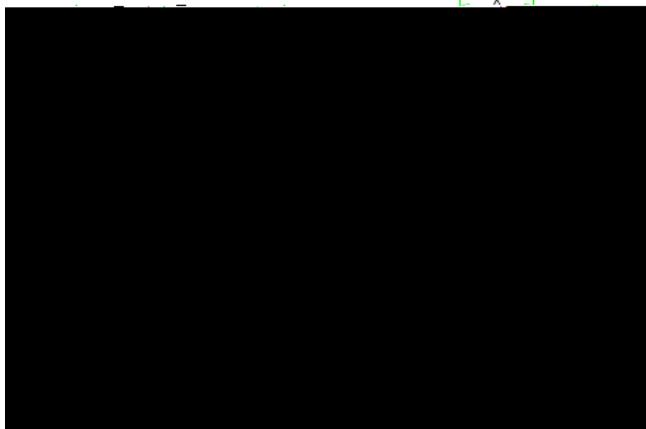
Figure 10. Maximum Drain Current vs. Case Temperature

Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient

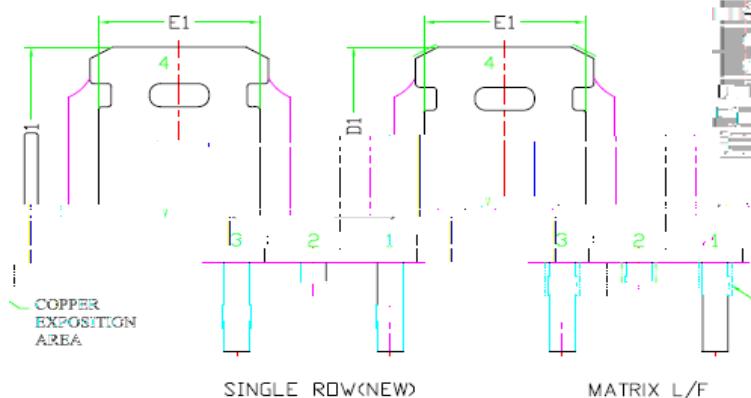
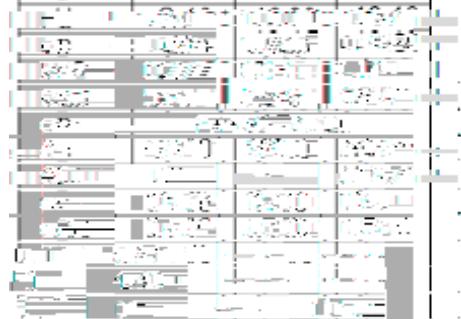


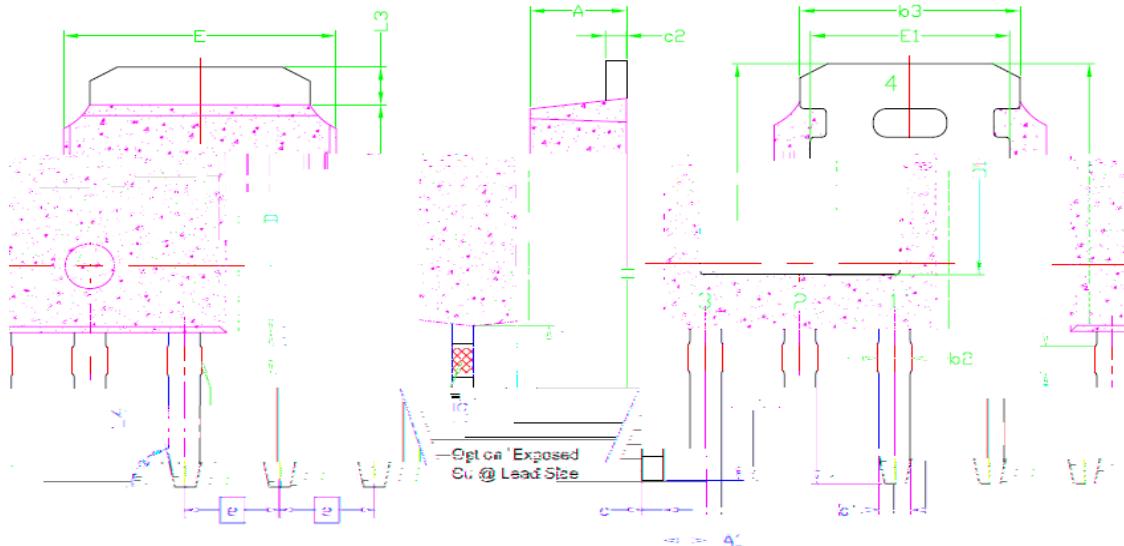
Package Outline

TO-252, 2 leads



SYMBOL	DIMENSIONAL REQMTS		
	MIN	NOM	MAX
E	6.40	6.60	6.731
L	1.40	1.52	1.77
L1	2.743	REF	
L2	0.508	BSC	
L3	0.89	--	1.27
L4	0.64	--	1.01
L5	--	--	--
D	6.00	6.10	6.223



Package Outline
TO-251, 3leads


SYMBOL	DIMENSIONAL REQMTS		
	MIN	NOM	MAX
E	6.40	6.60	6.731
L	3.98	4.13	4.28
L3	0.89	--	1.27
L4	0.698 REF		
L5	0.972	1.099	1.226
D	6.00	6.10	6.223
H	11.05	11.25	11.45
b	0.64	0.76	0.88
b2	0.77	0.84	1.14
b3	5.21	5.34	5.46
e	2.286 BSC		
A	2.20	2.30	2.38
A1	0.89	1.04	1.15
c	0.46	0.50	0.60
c2	0.46	0.50	0.60
D1	5.10	--	--
E1	4.40	--	--
α	79° REF		